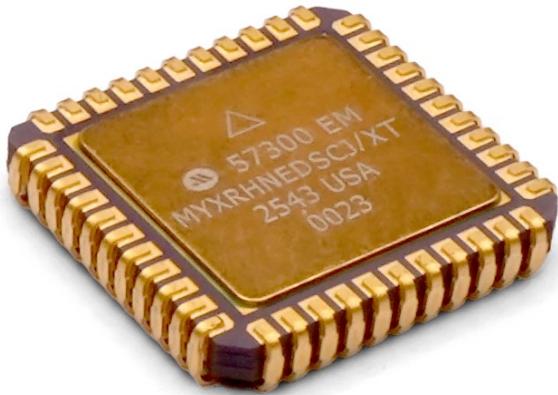


Standard-Performance NED

Nuclear Event Detector



Part Number: MYXRHNEDSCJ/EM, MYXRHNEDSCJ/XT, MYXRHNEDSCJ/H,



Preliminary Data Sheet

Micross' Standard-Performance Nuclear Event Detector (NED) features a 2X increase in radiation dose rate sensitivity and half the response times relative to legacy devices. The Micross part also has integrated differential drivers and receivers providing SWaP reduction, improved noise immunity and reduced delay times. The Standard-Performance NED is tested over the full-MIL temperature range (-55°C to 125°C) and provides a greatly improved functional replacement for the nearly 40-year-old legacy NED solution.

Key Features

- Gamma Dose Rate Sensitivity Threshold Range Adjustable from 1×10^5 to 2×10^7 rads (Si) / sec.
- 44-Pin Hermetic J-Lead SMT Package (.650in x .650in x .113in)
- Integrated Differential Line Drivers and Receivers Eliminates the Need for Shielding External Drivers and Receivers
- Radiation Specifications
 - Total Dose (Device Survivability): 1×10^6 rads(Si)
 - Dose Rate (Operate Through): 2×10^9 rads(Si)/sec
 - Neutron Fluence (Device Survivability): 5×10^{13} neutrons/cm²
- Delay from Radiation Detected to Output Signal Asserted: 7 ns at 10X Overdrive, 5nS at 50X overdrive
- 3.3V Power Requirement
- -55°C to +125°C Temperature Range
- Available in Micross Class XT and MIL-PRF-38534 Class H

Benefits

- Low Minimum Dose Rate Sensitivity
- Fast Delay Time to Enable Rapid Shutdown and Minimize Damage to Other Electronics
- Rad-Hard for Strategic Environments
- Small Compact Package Facilitates Use on Densely Populated Circuit Boards
- Built-In Differential Drivers and Receivers Provide SWaP (Space, Weight & Power) Savings, Improved Noise Immunity, and Reduced Delay Times
- Use Output Signal to Shut Down Power Supplies, Take Processors Offline and Block Memory Write Operations

Applications

- Aircraft and Drones
- Defense Weapon Systems
- Satellites
- Military Ground Vehicles
- Nuclear Material Storage

Revision History

Revision	Description	Release Date
0.1	Initial Draft of Preliminary Datasheet	06/04/2025
1.0	Revised, including addition of application information	6/26/2025
1.1	Changed package type from non-hermetic to hermetic; Added reference to case ground pin; BIT pulse time; graphs for $R_{REF-ADJ}$ and C_{PULSE} ; added mention about delay time test.	7/24/2025
1.2	Corrected error in signal polarities for NED_DET, NED_FLG and NED_RST differential signals. Added package top view diagram including signal names	9/12/2025
1.3	Performance documentation following testing	12/10/25
1.4	Miscellaneous Documentation Updates	12/18/2025

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1.0 Description

Micross Standard-Performance Nuclear Event Detector (NED, Figure 1) provides an economical solution for detecting gamma radiation pulses from a nuclear event. For an overdrive ratio of just 2 (ratio of received radiation-to-dose rate threshold), the NED will assert its pulse and level differential output signals within 20ns following the leading edge of an incoming gamma radiation pulse. This response time drops to as little as 5nS with overdrive approaching 50X. The NED's level output may then be reset by the assertion of a differential input signal. The MYXRHNEDSCJ/X features a minimum dose rate threshold of 1×10^5 rads(Si)/sec, thereby providing higher sensitivity than currently available NEDs. Users can increase the dose rate threshold upwards, to up to 2×10^7 rads(Si)/sec, by means of an external adjustment resistor. The Standard Performance NED, which is available in a hermetic 44-pin J-Lead ceramic package, is radiation hardened, enabling it to operate reliably in environments with high gamma doses and dose rates, neutrons and heavy ions; and provides immunity to latch up. It achieves this by using a rad-hard-by-design ASIC designed specifically for this purpose. Since the ASIC contains the line drivers and receivers on-board as Rad Hard blocks, no additional consideration is need for those functions.

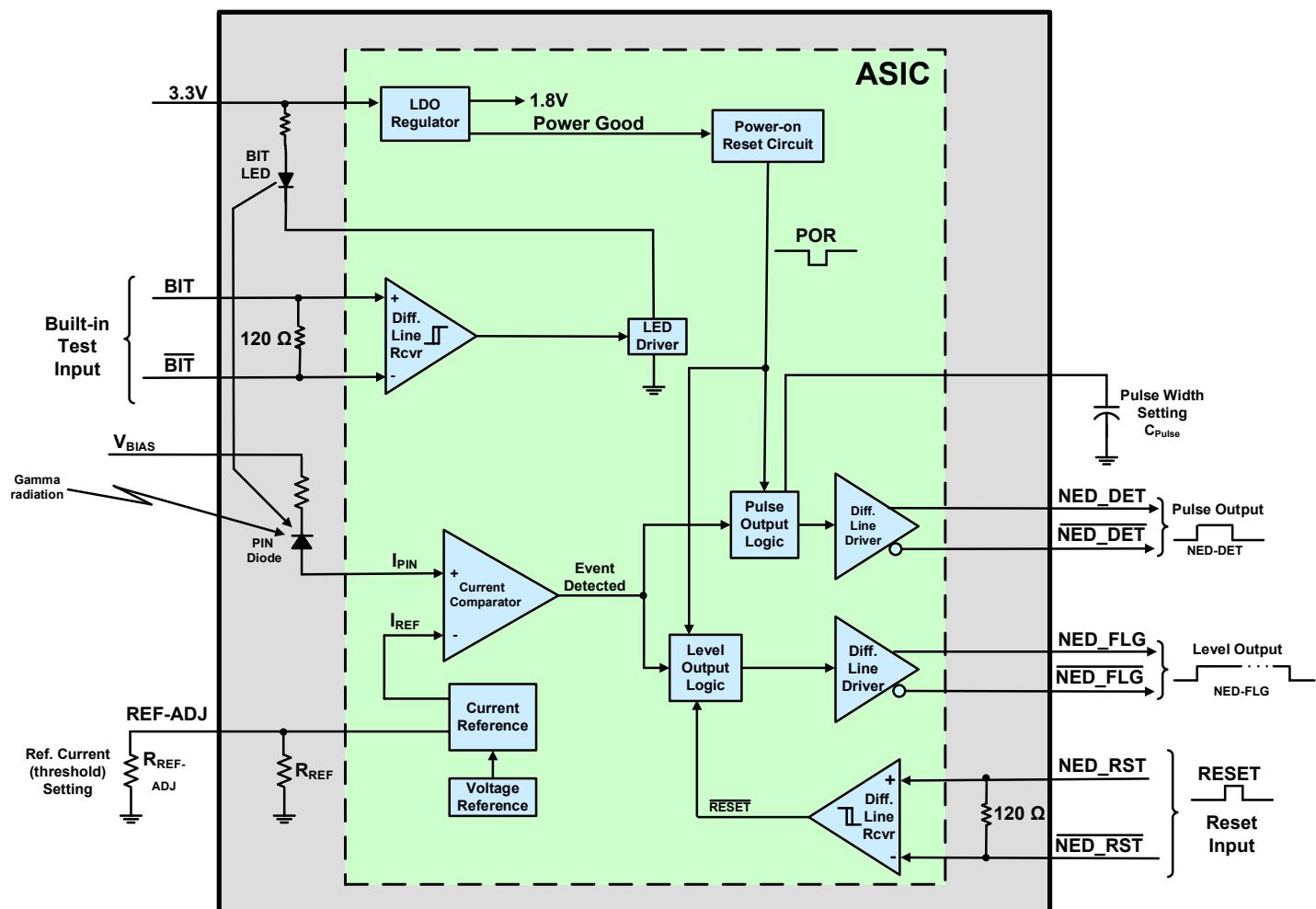


Figure 1. Nuclear Event Detector (NED) Block Diagram

2.0 Specifications

Table 1 provides the absolute maximum ratings for the MYXRHNEDSCJ/X nuclear event detector (NED), while Table 2 provides the electrical and mechanical specifications and characteristics.

Table 1. Absolute Maximum Range			
Parameter	Min	Max	Unit
Hardened Supply Voltage	-0.5	3.6	V
PIN Diode Bias Voltage	0	100	V
Differential Receivers Line Voltage	-8.0	8.0	V
Differential Drivers Line Voltage	-0.5	3.6	V
ESD Sensitivity	Class 2		
Junction Temperature, TJ	-55	150	°C
Storage Temperature Range	-65	150	°C
Total Dose (Device Survivability)		1×10^6	rads(Si)
Dose Rate (Operate Through)		2×10^9	rads(Si)/sec
Neutron Fluence (Device Survivability)		5×10^{13}	neutrons/cm ²
Dose Rate (Device Survivability)		1×10^{12}	rads(Si)/sec

Table 2. Electrical Specs and Characteristics

Parameter	Symbol	Conditions	Min	Max	Unit	Group A Subgroups
Approximate Dose Rate Threshold Adjustment Range		$V_{BIAS} = 15$ volts	1×10^5	2×10^7	Rads(Si)/sec	
Dose Rate Threshold Variation Over Temperature		Relative to Room Temperature Threshold Over Temperature Range	-20	+20	%	
Hardened Power Supply Operational Voltage	V_{CC}		3.0	3.6	V	1,2,3
Hardened Power Supply Current Both differential driver output circuits unterminated or AC-coupled terminated	I_{CC}	Notes 1,2 $V_{CC} = 3.3V$		5		
One differential driver output circuit DC-coupled terminated				35	mA	1,2,3
Both differential driver output circuits DC-coupled terminated				65		
PIN Diode Bias Voltage	V_{BIAS}		3.3	100	V	1,2,3,5

Table 2. Electrical Specs and Characteristics Cont.

Parameter	Symbol	Conditions	Min	Max	Unit	Group A Subgroups
PIN Diode Bias Current Standby	I_{BIAS}			10	μA	1,2,3
Radiation Propagation Delay Time Gamma Dose Rate = 2×10^5 rads(Si)/second Gamma Dose Rate = 2×10^7 rads(Si)/second	t_D	At 10X overdrive, Notes 3,4 $V_{BIAS} = 15$ Volts		7 5	ns ns	
Differential Receivers' Voltage Threshold	V_{DR}	$V_{CC} = 3.3V$	-0.2	0.2	V_{PK}	1,2,3
Differential Receivers' Common Mode Voltage Range	V_{CM}	$V_{CC} = 3.3V$	-7.0	7.0	V	1,2,3
Differential Receivers' Hysteresis Voltage	$V_{RX-HYST}$	$V_{CC} = 3.3V$	50 typ.		mV	1,2,3
Differential Line Driver Differential Output Voltage	V_{DT}	$V_{CC} = 3.3V$	3.0	10.0	$V_{PK-to-PK}$	1,2,3
Pulse Output Pulse Width Range	t_{PULSE}	Adjustable by External Capacitor	0.1		ms	
NED-RST (RESET) Pulse Width	t_{RESET}		1.0		μs	9,10,11
NED-RST asserted to NED_FLG de-asserted	$t_{RESET-to-FLG}$		300 (typ)		ns	
BIT Pulse Width	t_{BIT}		10		μs	
Operating Temperature Range	$T_{OPERATION}$		-55	+125	°C	
Package			Ceramic BGA			
Outline Dimensions			17.11 x 17.55 x 3.05 typ. (0.691 x 0.691 x 0.12) typ.		mm (in)	
Mass (Weight)			1.0 typ. (0.035 typ.)		g (oz)	
Lot Qualification and Acceptance Testing			XT, or in accordance with MIL-PRF-38534 Class H			

Notes:

1. The maximum values for I_{CC} assume the dose rate threshold is set to its minimum value of 1×10^5 rads(Si)/sec. For the external adjustment threshold resistor selected for the maximum dose rate threshold of 2×10^7 rads(Si)/sec, the max. value of I_{CC} increases by 7 mA. Refer to section 3.5.
2. For the NED and NEF line drivers, the termination loads on the line drivers are assumed to be 120 ohms differential (resistive). The use of terminations with series capacitors will reduce power dissipation accordingly.
3. Dose rate threshold is set to its minimum value of 1×10^5 rads(Si)/sec. Internal dose rate minimum setting may not be present in /EM units, consult factory.

4. Delay time t_D is defined as the time from the 50% point of the rising edge of the incoming gamma radiation pulse to the 50% point of the high-to-low voltage transition for the NED-DET and NED-FLG differential output signals.
5. Unit sensitivity is specified at 15V PIN diode bias.

3.0 Operation

3.1 ASIC-Based Design

Micross' ASIC-based design provides multiple benefits relative to legacy nuclear event detectors:

1. It enables construction of a NED in a smaller and lighter package, capable of surviving prompt dose radiation.
2. Inclusion of differential drivers on chip improves overall response time, while legacy products suffer further response time degradation when external drivers are added.
3. By greatly reducing the number of components, wire bonds and interconnects, the Micross NEDs' reliability (MTBF) will be significantly higher than that of other NEDs.
4. Use of sub-micron ASIC technology and operation from lower power supply voltages will reduce the NED's power consumption and dissipation.
5. As a means of mitigating against obsolescence, Micross is not dependent on third-party suppliers for key components.
6. Micross' selected trusted foundry is on-shore and offers a 180 nm process with the capability to produce chips that meet the NED's radiation requirements. These requirements are:
 - Total gamma dose: 300 krads (Si), with a goal of 1 Mrads(Si)
 - Gamma dose rate (operate-through): 2×10^9 rads(Si)/sec
 - Neutron fluence: 10^{13} n/cm²

3.2 Functional Overview

As shown in Figure 1, the MYXRHNEDSCJ/X NED includes a 3.3V-to-1.8V LDO regulator. With the exception of the PIN diode and the two differential line drivers, all circuitry in the NED is powered by the ASIC's 1.8V supply rail. The two differential line drivers are powered directly by the 3.3V input power.

The NED includes a PIN diode to sense incoming gamma radiation from a nuclear explosion. Gamma radiation will result in current flowing through the reverse-biased PIN diode into the "+" side of a current comparator.

The input to the "-" side of the current comparator is provided by a reference circuit. This reference current is user-adjustable by means of the external resistor $R_{REF-ADJ}$ (see Figure 1 and section 3.5). As explained in section 3.5, installing a lower value for $R_{REF-ADJ}$ will increase the value of the reference current and as a result, increase the value of the NED's dose rate threshold.

When the PIN diode current exceeds the reference current, the output state of the comparator will assert active, indicating that a nuclear event has been detected.

Following power turn-on, when the 1.8V regulator senses that its output has exceeded a voltage of approximately 1.0 volt, it will assert its POWER GOOD output signal. This will result in the generation of a negative-going "POR" (power-on reset) pulse. This pulse will reset the NED's two differential outputs NED and

NEF to their quiescent (inactive) states of logic “1”. Once this occurs, the NED and NEF outputs will remain in their de-asserted states (high) until a nuclear event is detected.

Following the detection of a nuclear event, NED-DET and NED-FLG will transition from their quiescent, de-asserted states of logic “0” (low) to their active, asserted states of logic “1” (high). The NED-DET pulse output will assert low for a fixed amount of time, as determined by the value of an external capacitor (see Figure 1 and section 3.8). The NED-FLG (latched flag) output will remain asserted until the receipt of a negative going pulse on the RESET differential input. A logic “1” pulse on the RESET input of duration 1.0 μ s or more will clear the NED_FLG output back to its de-asserted state.

3.3 PIN Diode

Similar to most existing NED designs, the sensing element in Micross’ Nuclear Event Detector is a PIN diode. Most commercially available PIN diodes targeted to sensing applications are designed to operate at longer wavelengths, such as RF, visible, infrared, ultraviolet and X-ray. In particular, they’re not designed to be optimized for detecting gamma radiation. For use in its NED, Micross has designed and fabricated its own PIN diode that’s optimized for detecting gamma radiation. This internal development and captive manufacturing will ensure Micross with a reliable supply of PIN diodes, providing very strong mitigation against future obsolescence.

For its PIN diode development, Micross Components focused on the goals of wide dynamic range and fast response time in response to short duration pulses of gamma radiation. The PIN diode development involved extensive testing and characterization of the PIN diode in a flash X-ray facility.

To provide a reverse bias voltage to the NED’s PIN diode, it’s highly recommended to apply a minimum voltage of +15V to the PIN_Diode_Bias input (V_{BIAS}). Although it’s possible to operate the NED from a lower value of V_{BIAS} , this will reduce the NED’s sensitivity and therefore increase its dose rate threshold. For instance, operating with a bias of 5V will decrease sensitivity by approximately 30%. It’s also possible to reduce the NED’s minimum dose threshold level and response time to a nuclear event by increasing the value of this voltage above 15V.

3.4 Detector Circuit

In addition to the PIN diode, the most critical functional block of the NED is its detector circuit. For this function, Micross includes a current comparator circuit in its NED ASIC. In contrast to the voltage comparator used in legacy NEDs, Micross’ use of a current comparator provides better speed performance by minimizing the impedance seen by the detector. This minimizes the value and effect of the circuit’s inherent RC time constant.

The detector circuit includes a reference current circuit. The reference circuit provides a DC current output based on the input from a precision voltage source. To allow users to set the value of the NED’s dose rate threshold, the reference current and therefore the dose rate threshold is programmable by means of an external resistor. The reference current circuit includes temperature compensation to offset temperature-dependent variations in the PIN diode and the current comparator. One of the goals for the detector’s current comparator circuit is to provide very fast detection speed that’s largely independent of the NED’s threshold sensitivity setting.

Based on the use of a custom PIN diode and the inherent advantages of a current comparator, the MYXRHNEDSCJ/X provides superior performance for minimum dose rate threshold and delay time performance.

The MYXRHNEDSCJ/X provides a minimum dose rate threshold of to 1×10^5 rads(Si)/sec or lower. The major benefit of this is to detect the fast-rising edge of the nuclear event sooner and to reduce the number of false negatives.

Relative to other NEDs, the MYXRHNEDSCJ/X also provides a significant improvement for the overall delay time between the leading edge of a gamma radiation pulse and the assertion of its output signal. The MYXRHNEDSCJ/X will reduce the value of this internal time delay to 20 ns with an overdrive ratio of 2. This delay time can be reduced to 5nS or less by increasing overdrive by 50X or more. Less overdrive is needed at higher dose rates. For instance, with a threshold of 2×10^7 , the response time is 15nS with only 20% overdrive. For users, NED delay time is a critical parameter, since shorter delays enable improved protection of other on-board electronic circuitry. Figure 3 shows how overdrive reduces response time.

3.5 Variable Dose Rate Threshold

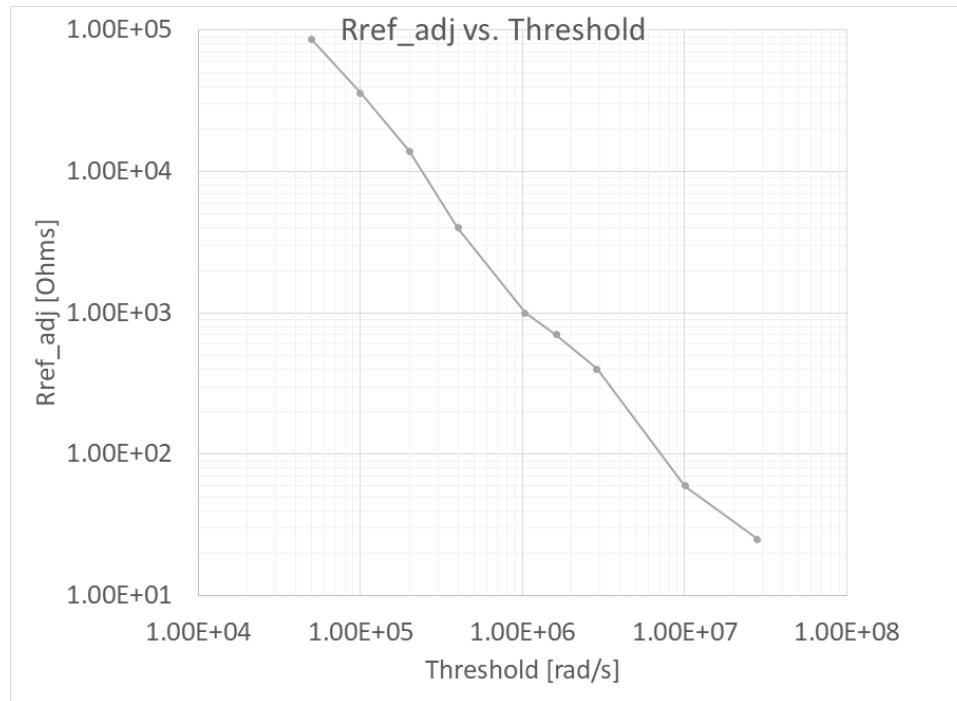
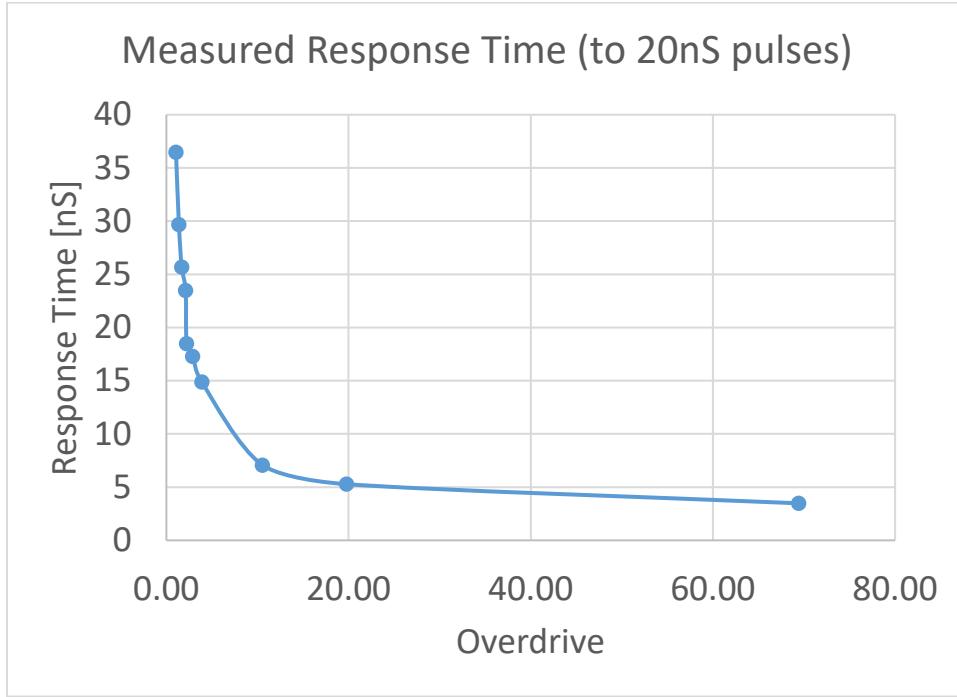
As shown in Figure 1, the NED provides a means to program the value of its dose rate threshold. This is done by connecting a resistor designated as $R_{REF-ADJ}$ between the signal $R_{REF-ADJ}$ and GROUND. If no resistor is connected between $R_{REF-ADJ}$ and GROUND, the dose rate threshold defaults to its minimum value of approximately 1×10^5 rad(Si)/sec. To configure the NED for a higher value of dose rate threshold, it's necessary to connect an external resistor between $R_{REF-ADJ}$ and GROUND. Note that /EM parts may not include an internal setting resistor. Consult factory when using /EM parts.

The graph of Figure 2 shows the relationship between dose rate threshold and the value of the adjustment resistor.

3.6 Differential Line Drivers and Receivers

As shown in Figure 1, the MYXRHNEDSCJ/X includes differential line drivers and receivers for the various digital output and input signals. It includes differential drivers for the NED pulse output and NEF level output, and differential receivers for the RESET and BIT input signals.

Differential drivers and receivers provide improved signal integrity, noise rejection and common mode rejection relative to single-ended drivers and receivers, especially single-ended drivers consisting of open-collector or open-drain circuits. Micross designed the differential drivers and receivers to provide reliable operation in the presence of the types of noise transients that occur during nearby nuclear events. To lessen the effects of noise, the receivers include built-in circuit protection, hysteresis and common mode rejection. The NED's differential drivers and receivers are designed to meet or exceed the requirements of the EIA RS-422 standard. For the transmitter outputs, this will include a minimum differential output voltage of 3.0 volts peak-to-peak.

**Figure 2. Dose Rate Threshold Adjustment Resistor****Figure 3. Response Time vs Overdrive**

The differential receiver for the RESET input will be biased to provide a logic “1” (inactive) output when there’s no incoming signal, while the differential receiver for the BIT (Built-in Test) input will be biased to provide a logic “0” (inactive) output when there’s no incoming signal. In addition, the differential receivers will include positive

and negative threshold voltages of less than ± 0.2 V peak, provide a minimum hysteresis voltage of 50 mV and operate with common mode voltages equal to or greater than the range of -7V to +7V.

The external signals for the differential and single-ended line drivers and receivers will include clamping diodes to V_{CC} and GROUND to protect against electrostatic discharge (ESD).

The delays through the MYXRHNEDSCJ/X's on-ASIC differential line drivers are less than 5 ns. Note that other NEDs provide single-ended open-collector drivers rather than differential drivers. In order to gain the benefit of differential signaling using these NEDs, it's necessary to use external differential drivers. For the MYXRHNEDSCJ/X, the inclusion of the internal differential drivers provides a large speed improvement over the use of external drivers, which can add additional delays of approximately 15 ns.

To ensure reliable operation of the NED_H and NED_L differential pulse type output and/or the NEF_H and NEF_L differential level type output, it's necessary to terminate the end of the differential cable going into a differential receiving circuit with a resistor that matches the cable's differential characteristic impedance. For signals adhering to the RS-422 standard, the standard value for the cable characteristic impedance and terminating resistance is 120 ohms.

3.7 Differential and Single-Ended Operation

The NED's BIT and RESET inputs, and NED_DET and NED_FLG outputs can be operated as either differential pairs or as single-ended signals. As shown in Figure 1, to operate the BIT and/or RESET inputs in differential mode, it's recommended to connect a 120 ohm termination resistor between BIT and \overline{BIT} or between NED_RESET and $\overline{NED_RST}$.

To operate these inputs in single-ended mode, it is recommended to connect a termination resistor between the used input signal (e.g., BIT) and GROUND and to connect the unused input (e.g., \overline{BIT}) to a voltage of approximately $0.5 * V_{DD}$ through a simple resistive voltage divider.

Similarly, the NED's NED_DET and NED_FLG output signals can also be operated as either differential pairs or as single-ended signals. When operating NED_DET and $\overline{NED_DET}$ and/or NED_FLG and $\overline{NED_FLG}$ in differential mode, it's recommended to connect a termination resistor across the receiving end of the differential link. The value of this resistor should match the characteristic impedance of the interconnecting cable. For RS-422 type signals, cables with 120 ohm impedance are commonly used. To use these output signals in single-ended mode, it is recommended to connect a termination resistor (e.g., 120 ohms) between the used signal conductor (e.g., NED_H) and GROUND at the receiving end of the signal link.

3.8 NED_H/ $\overline{NED_DET}$ Pulse Width Setting

To program the pulse width duration from the NED_DET/ $\overline{NED_DET}$ differential output, connect a capacitor between the signal Pulse Width Cap. and ground. The value of this capacitor should be:

$$\text{Cap value} = \frac{\text{Pulse (sec)}}{16,000}$$

For example, for a pulse width = 100 μ s,

$$\text{Cap value} = \frac{0.0001}{16,000} = 6.25 \text{ nF}$$

The graph of Figure 5 shows the relationship between desired output pulse width and the value of the capacitor.

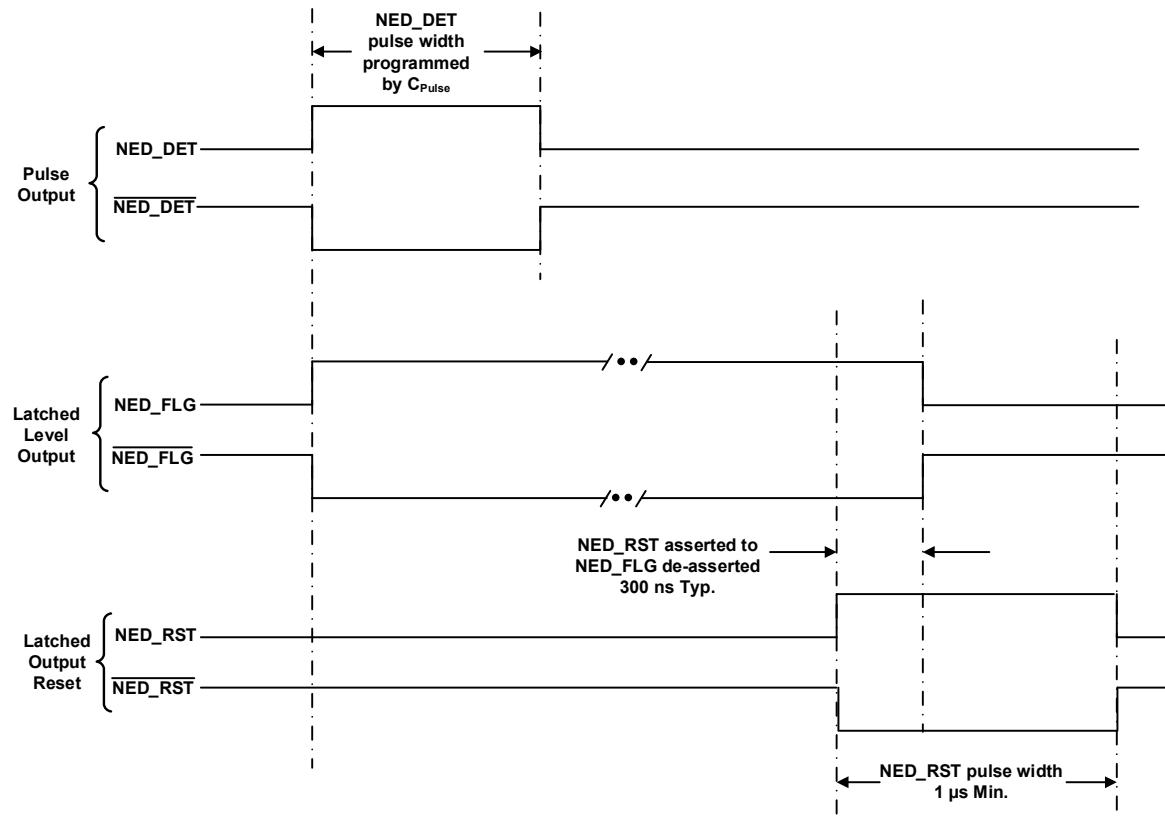


Figure 4. NED_DET (pulse), NED_FLG (latched level) and NED_RST (reset) Timing

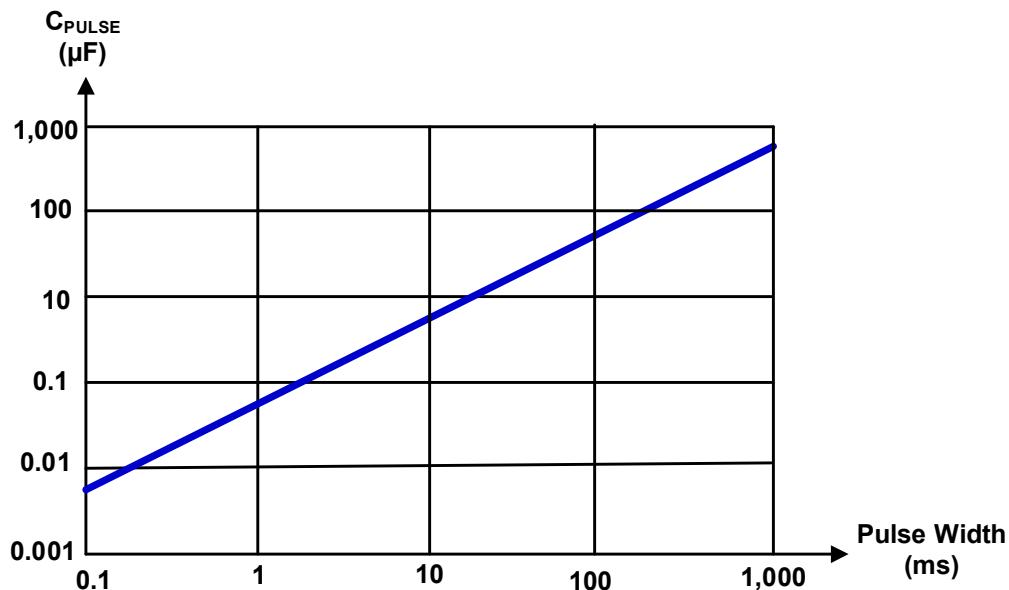


Figure 5. Pulse Width Capacitor

3.9 Built-In Self-Test

To enable Built-in self-test (BIT), the MYXRHNEDSCJ/X includes an LED. This LED will be controlled by the BIT (built-in test) differential input signal. When BIT is asserted to logic “1”, the LED will illuminate the PIN diode. During this test, if the NED-DET and NED-FLG output signals assert high, the self-test will be considered to have passed. However, if the NED-DET and NED-FLG signals remain inactive, this indicates that the has failed. To ensure that the NED-DET pulse output and NED-FLG latched level output assert during self-test, the differential BIT signal should be asserted for at least 10 μ s. In addition, it's recommended that the width of the BIT pulse be less than the value of the NED_DET output pulse that's programmed by the value of C_{PULSE} in Figure 1.

3.10 Radiation Testing

Each MYXRHNEDSCJ/X NED shipped will be tested for dose rate threshold and a radiation-to-output assertion time of approximately 20 ns at 2x overdrive.

3.11 Pinout and Signal Descriptions

Table 3 provides the pinout and signal descriptions for the NED.

Table 3. Signal Pinout and Descriptions

Pin Number	Signal Name	Input or Output	Description
1	N/C	--	No internal connection. Should connect to ground.
2	GROUND	--	GROUND
3	GROUND	--	GROUND
4	NED_DET	Output	

Table 3. Signal Pinout and Descriptions

Pin Number	Signal Name	Input or Output	Description
5	NED_DET	Output	NED differential pulse output. Quiescently, NED_DET outputs a low level and <u>NED_DET</u> outputs a high level. When the NED detects a nuclear event, NED_DET transitions to a high level and <u>NED_DET</u> transitions to a low level for the programmed duration of the pulse output. The length of the pulse is determined by the value of the external pulse width control capacitor connected between pin 14 and GROUND.
6	N/C	--	No internal connection. Should connect to ground.
7	GROUND	--	GROUND
8	GROUND	--	GROUND
9	N/C	--	No internal connection. Should connect to ground.
10	V _{DD}	Input	3.3V power input
11	V _{DD}	Input	3.3V power input
12	V _{DD}	Input	3.3V power input
13	N/C	--	No internal connection. Should connect to ground.
14	Pulse Width Cap.	--	As described in section 3.8, the duration of the NED's pulse type output asserted by the differential pair NED_DET and <u>NED_DET</u> needs to be configured by connecting a capacitor between Pulse Width Cap. and GROUND.
15	N/C	--	No internal connection. Should connect to ground.
16	N/C	--	No internal connection. Should connect to ground.
17	POR_cap	--	This pin may be left unconnected. However, it may be used to increase the NED's power-on reset time. To do that, connect an external capacitor between POR_cap and GROUND.
18	GROUND	--	GROUND
19	V _{REF}	--	Connects to internal reference voltage used for current comparator circuit. Do <u>not</u> connect to this pin.
20	N/C	--	No internal connection. Should connect to ground.
21	GROUND	--	GROUND
22	R _{REF-ADJ}	--	External resistor to adjust the NED dose rate threshold. To configure the NED for its minimum dose rate threshold of 1×10^5 rad(Si)/sec, this pin should be left open. As described in section 3.5, the NED's dose rate threshold can be adjusted to a higher value by connecting a resistor between R _{REF-ADJ} and GROUND. Note that /EM parts may not have an internal resistor connected, consult factory.
23	N/C	--	No internal connection. Should connect to ground.
24	BIT	Input	

Table 3. Signal Pinout and Descriptions

Pin Number	Signal Name	Input or Output	Description
25	BIT	Input	Differential Built-in Test (BIT) input. To perform the NED's built-in test, this differential signal should be asserted with BIT driven high relative to <u>BIT</u> . To determine if the NED has passed its built-in test, verify that the <u>NED_DET</u> / <u>NED_DET</u> pulses for the period programmed by the Pulse Width Cap. and that <u>NED_FLG</u> / <u>NED_FLG</u> asserts its latched level output until <u>NED_RST</u> (RESET) is asserted. To ensure that the <u>NED_DET</u> pulse and <u>NED_FLG</u> latched outputs assert during self-test, the differential BIT signal should be asserted for at least 10 μ s.
26	N/C	--	No internal connection. Should connect to ground.
27	NED_RST	Input	Differential NED Reset input. For normal operation, <u>NED_RST</u> should be asserted low and <u>NED_RST</u> should be asserted high. Following detection of a nuclear event, the <u>NED_FLG</u> / <u>NED_FLG</u> latched differential level output will assert. To clear the <u>NED_FLG</u> / <u>NED_FLG</u> output, it's necessary to assert the <u>NED_RST</u> input. This is done by driving <u>NED_RST</u> high and <u>NED_RST</u> low for a minimum time of 1.0 μ s.
28	<u>NED_RST</u>	Input	<u>Notes:</u> <ol style="list-style-type: none"> 1. If the <u>NED_RST</u>/<u>NED_RST</u> input is asserted, this will prevent the <u>NED_FLG</u>/<u>NED_FLG</u> output from asserting. 2. The <u>NED_RST</u>/<u>NED_RST</u> input has <u>no</u> effect on the <u>NED_DET</u>/<u>NED_DET</u> pulse output.
29	1.8V	Input	Internal 1.8V output. Do <u>not</u> connect to this pin.
30	N/C	--	No internal connection. Should connect to ground.
31	N/C	--	No internal connection. Should connect to ground.
32	GROUND	--	GROUND
33	GROUND	--	GROUND
34	N/C	--	No internal connection. Should connect to ground.
35	PIN_Diode_Bias	Input	PIN Diode Bias. In order to meet speed and sensitivity specifications it's necessary to apply a minimum voltage of +15V to the <u>PIN_Diode_Bias</u> input. It's possible to reduce the NED's response time to a nuclear event by increasing the value of this voltage.
36	N/C	--	No internal connection. Should connect to ground.
37	N/C	--	No internal connection. Should connect to ground.
38	Case Ground	--	Case ground. It is recommended to connect this pin to chassis ground.
39	N/C	--	No internal connection. Should connect to ground.

Table 3. Signal Pinout and Descriptions

Pin Number	Signal Name	Input or Output	Description
40	N/C	--	No internal connection. Should connect to ground.
41	V_{PIN_Diode}	--	Internal connection to a resistor that connects between the PIN diode and the ASIC. Do <i>not</i> connect to this pin.
42	N/C	--	No internal connection. Should connect to ground.
43	NED_FLG	Output	NED latched flag output. Quiescently, NED_FLG outputs a low level and $\overline{NED_FLG}$ outputs a high level. When the NED detects a nuclear event, NED_FLG transitions to a high level and $\overline{NED_FLG}$ transitions to a low level. The state of this differential output signal is internally latched and the output remains asserted until the NED_RST input is asserted by driving NED_RST high and $\overline{NED_RST}$ low for a minimum of 1.0 μ s.
44	$\overline{NED_FLG}$		

4.0 Application Information

4.1 Input Signals

The NED includes two pairs of differential input signals: the NED_RST and $\overline{NED_RST}$ (RESET) inputs for resetting the flag (level type) output signal and the BIT and \overline{BIT} inputs for activating built-in test. These signals may be operated as either differential pairs or as single-ended signals.

4.1.1 Differential Inputs

For operating the RESET and BIT signals as differential pairs, the signal pairs should be terminated with 120 ohm resistors as shown in Figure 6. To reduce power dissipation by the differential drivers from an external circuit, it's recommended to include a capacitor (C_{TERM}) in series with the termination resistor, as shown in Figure 6(b). This prevents the need for the driving circuit to provide current except during signal transitions between its high and low states. To minimize reflections, it's recommended that the RC time constant of the series RC termination be approximately equal to or greater than the incoming signals' maximum anticipated rise and fall times.

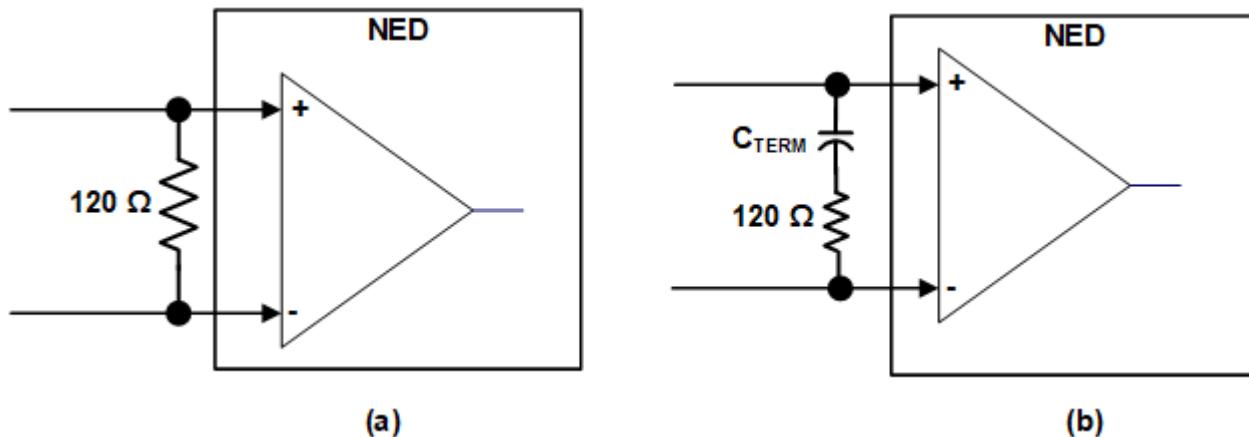


Figure 6. Differential Input Signal Termination
(a) Simple Termination; (b) AC-Coupled Termination

As shown in Figure 7, the NED's BIT and RESET input signals can be operated as single-ended inputs. This requires that a reference voltage of approximately $V_{CC}/2 = 1.65V$ be applied to the NED's \overline{BIT} or $\overline{NED_RST}$ input signal. In order to minimize power consumption for the driving circuit, similar to the circuit for differential input signals, it's recommended to include a series capacitor in series with the termination resistor, as shown in Figure 7(b). To minimize reflections, it's recommended that the RC time constant of the series RC termination be much greater than the anticipated signal rise and fall times. For example, an $0.1 \mu F$ capacitor will provide a time constant of $12 \mu s$, much longer than the maximum anticipated rise and fall times.

4.1.2 Single Ended Inputs

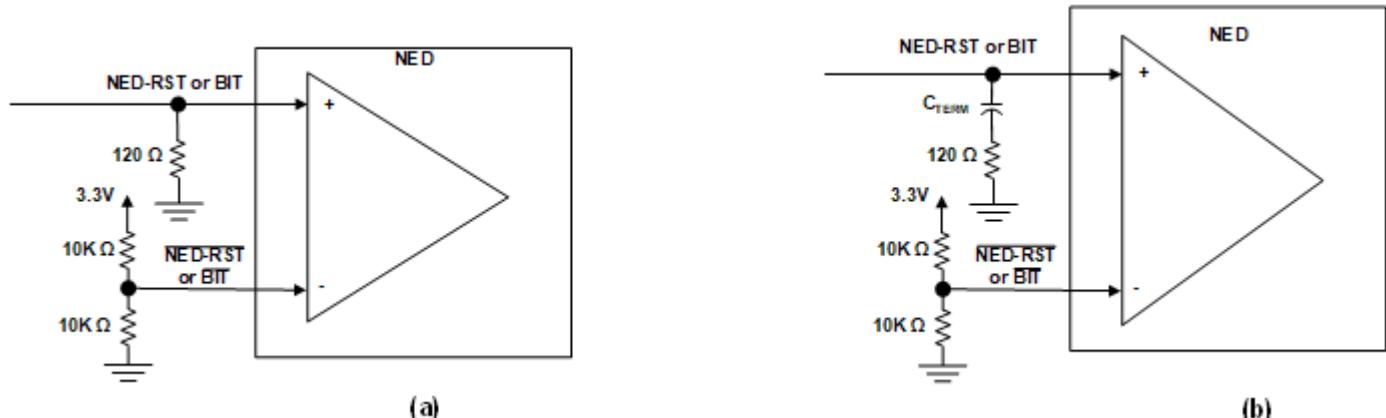


Figure 7. Single-Ended Input Signal Termination
(a) Simple Termination; (b) AC-Coupled Termination

4.2 Output Signals

The NED includes two pairs of differential output signals: NED_DET and NED_DET, which provide a differential pulse output that asserts following detection of a nuclear event; and NED_FLG and NED_FLG, which provide a latched flag differential output that also asserts following detection of a nuclear event. For the case of NED_FLG and NED_FLG, the latched flag output is de-asserted following reception of a minimum 1.0 μ s pulse to the NED_RST and NED_RST differential RESET input.

Like the NED's input signals, its differential outputs may also be operated as single-ended signals.

4.2.1 Differential Outputs

For operating the NED_DET and NED_FLG outputs as differential pairs, the signal pairs should be remotely terminated with 120ohm resistors as shown in Figure 8. To reduce power consumption and dissipation by the NED's differential drivers, it's strongly recommended to include a capacitor (C_{TERM}) in series with the termination resistor, as shown in Figure 8(b). This prevents the need for the NED drivers to supply current except during signal transitions between their high and low output states. This will reduce the NED's 3.3V current drain from 35 mA to 5 mA for the case where either the NED_DET or NED_FLAG differential output (but not both) are terminated by a simple 120 ohm resistor, or from 65 mA to 5 mA for the case where both the NED_DET and NED_FLAG differential outputs are terminated by simple 120 ohm resistors. To minimize reflections, it's recommended that the RC time constant of the series RC termination be approximately equal to or greater than the signals' maximum anticipated rise and fall times.

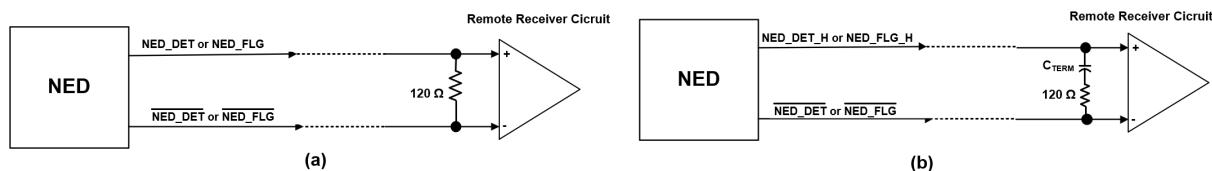


Figure 8. Differential Output Remote Signal Terminations
(a) Simple Termination; (b) AC-Coupled Termination

4.2.2 Differential Outputs

As shown in Figure 9, the NED's NED DETECT and NED FLAG output signals can be operated as single-ended outputs. This calls for a 120 ohm termination between the signal and ground at the remote receiver circuit. In order to minimize power consumption for the NED driver, similar to the circuit for differential output signals, it's recommended to includes a series capacitor in series with the termination resistor, as shown in Figure 9(b).

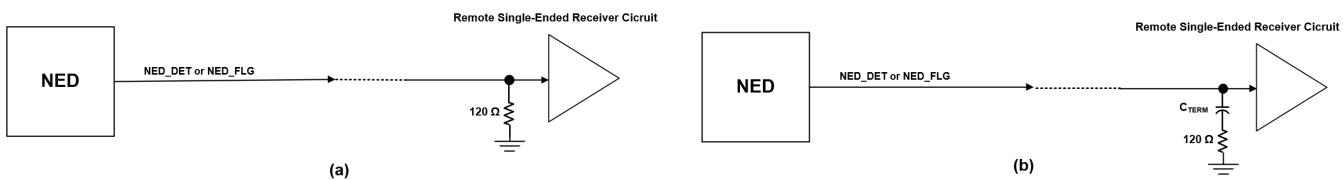


Figure 9. Single-Ended Output Remote Termination
(a) Simple Termination; (b) AC-Coupled Termination

4.3 Power Supply Crowbarring

One of the primary functions of the NED is to protect non-radiation hardened electronics from the effects of prompt dose radiation following a nuclear event. As shown in Figure 10, this involves using the NED output signal to activate a crowbar circuit to remove power from non-hardened circuits.

In Figure 10, the NED and crowbar circuit are powered by a hardened power supply. This is necessary to ensure that power for the NED itself and the crowbar circuit are able to operate through a nuclear event and the ensuing circumvention period by maintaining its output voltage.

Either the NED's pulse output (NED_DET/NED_FLG) or latched flag output (NED_FLG/NED_FLG) may be used for activating the power supply crowbar circuit. The pulse output provides a fixed duration time period to remove power from non-hardened loads, while the latched flag output requires a hardened processor, FPGA or other circuit to deactivate the crowbar and restore power to non-hardened loads.

The crowbar circuits themselves must be built using radiation hardened components. In the example shown in Figure 9, the crowbar circuit operates by simultaneously disconnecting the power supply and providing a rapid discharge path to ground for decoupling capacitors for power voltages for non-hardened load circuits. If the power supply includes a digital disable input, the signal from the NED should be connected to it as shown. The resistor in series with the MOSFET connecting to ground limits the current when discharging large capacitors on the power supply output.

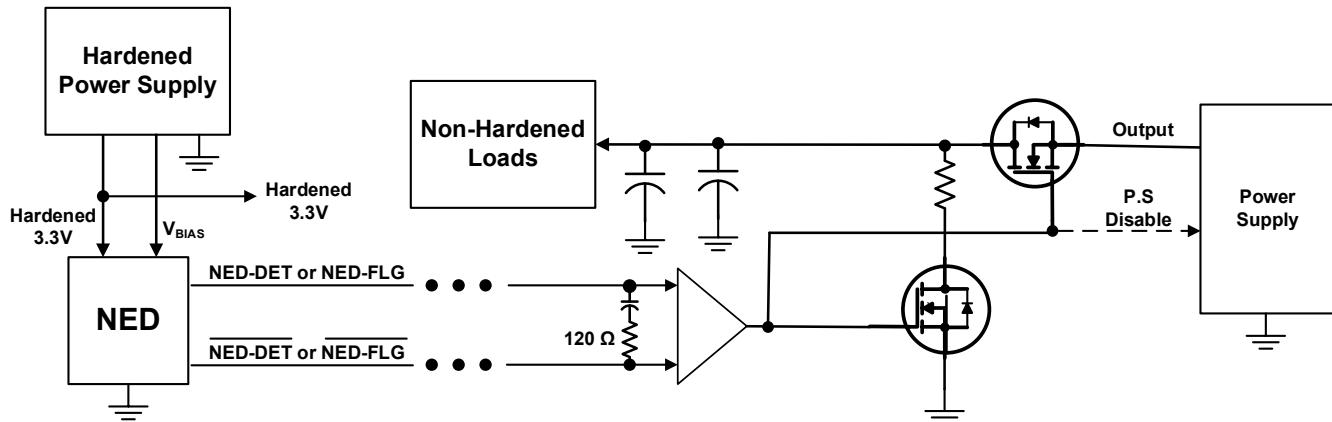


Figure 10. Using NED Output to Activate Power Supply Crowbarring

4.4 Shutting Down Processing

In addition to removing power from non-hardened electronics, another function of NEDs is to shut down digital processing following the detection of an event. As shown in Figure 11, this is done by connecting the NED's pulse or latched flag output to the input of a remote digital subsystem. As shown in this example, following the NED's detection of a nuclear event, the processing by a CPU or FPGA processor will be temporarily halted. In addition,

this circuit includes a provision to prevent writing corrupt data to RAM or MRAM memory during the circumvention period.

If the NED_H and NED_L (pulse output) signals are used, the circumvention period is defined by the width of the NED_H/ NED_L pulse. This period is user-programmable by the selection of the PULSE WIDTH CAP (Figure 1 and Figure 4) connected between the NED's pin 14 and ground. If the NEF_H and NEF_L (NED latched flag outputs) are used, then it will be necessary to assert the NED RESET signal at the end of the circumvention period. The circumvention period timing logic shown in Figure 9 will need to be hardened in order to operate reliably through the shut-down period for the processor and memory write logic.

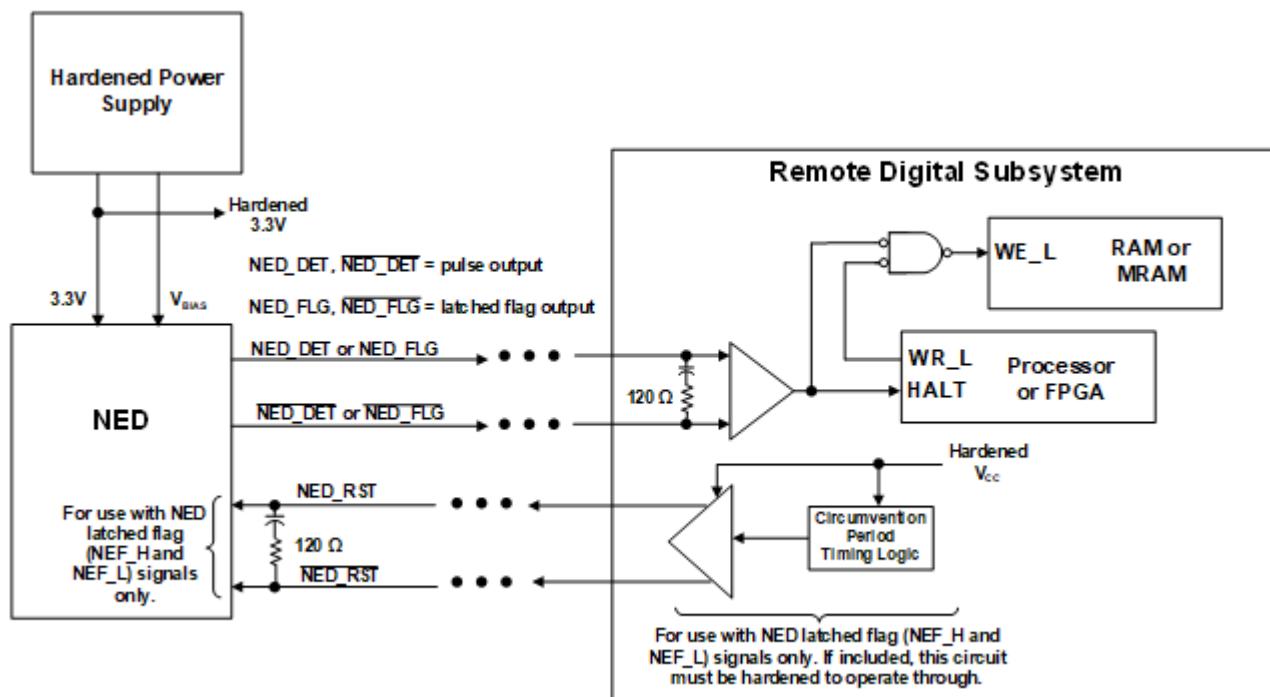


Figure 11. NED Output Shuts Down CPU and Memory Write Operations

5.0 Packaging

For the MYXRHNEDSCJ/X, the package size is a 17.53 x 17.53 x 3.05 mm (0.690 x 0.690 x 0.12 in.), a 44-pin J-lead surface mount ceramic package. Figure 12 is the package outline drawing, while Figure 13 is the recommended PC board pad placement diagram. Figure 14 provides the package top view pinout, including the signal names.

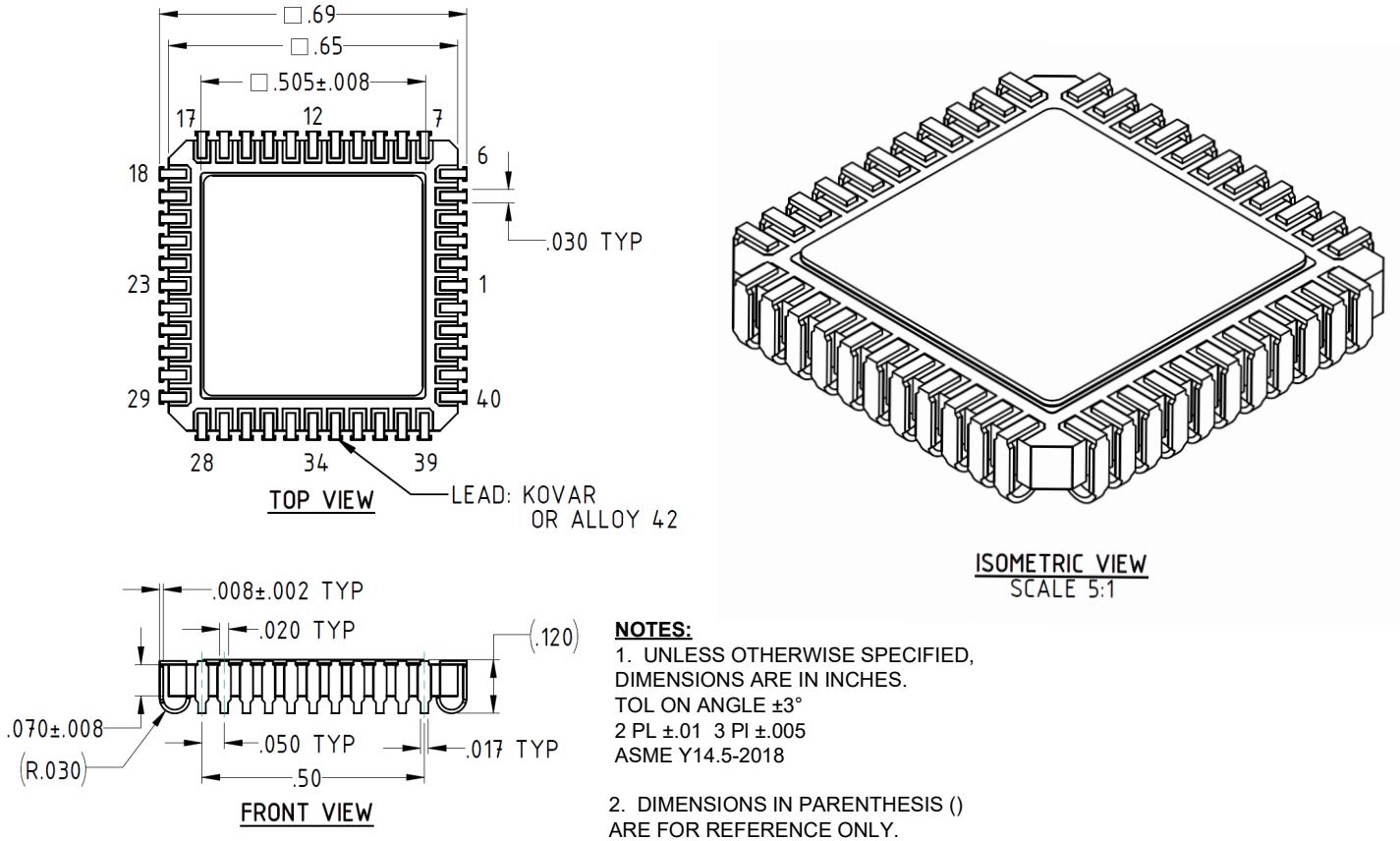


Figure 12. 44-pin J-Lead Surface Mount Package Outline

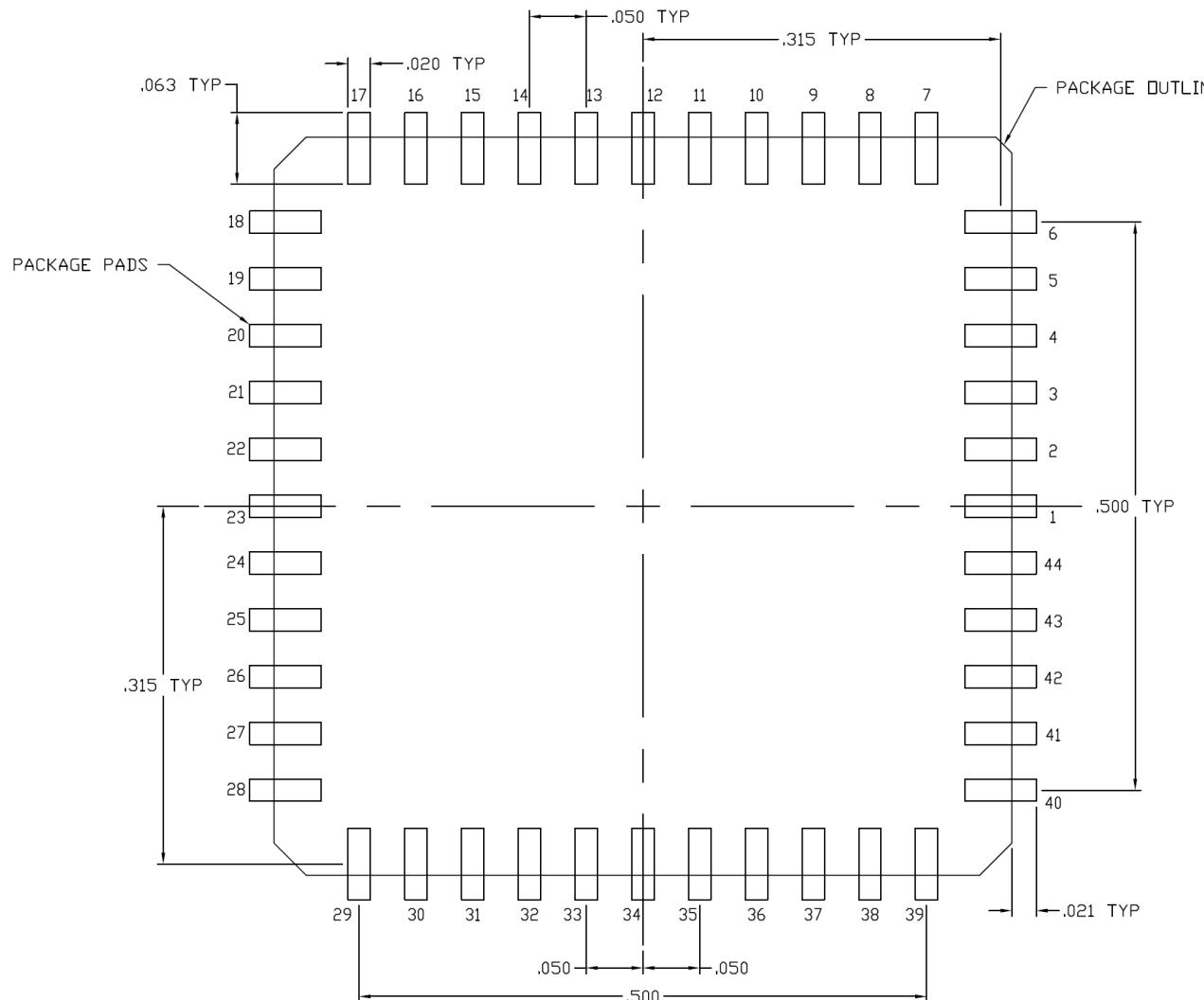


Figure 13. Recommended PC Board Pad Placement Diagram

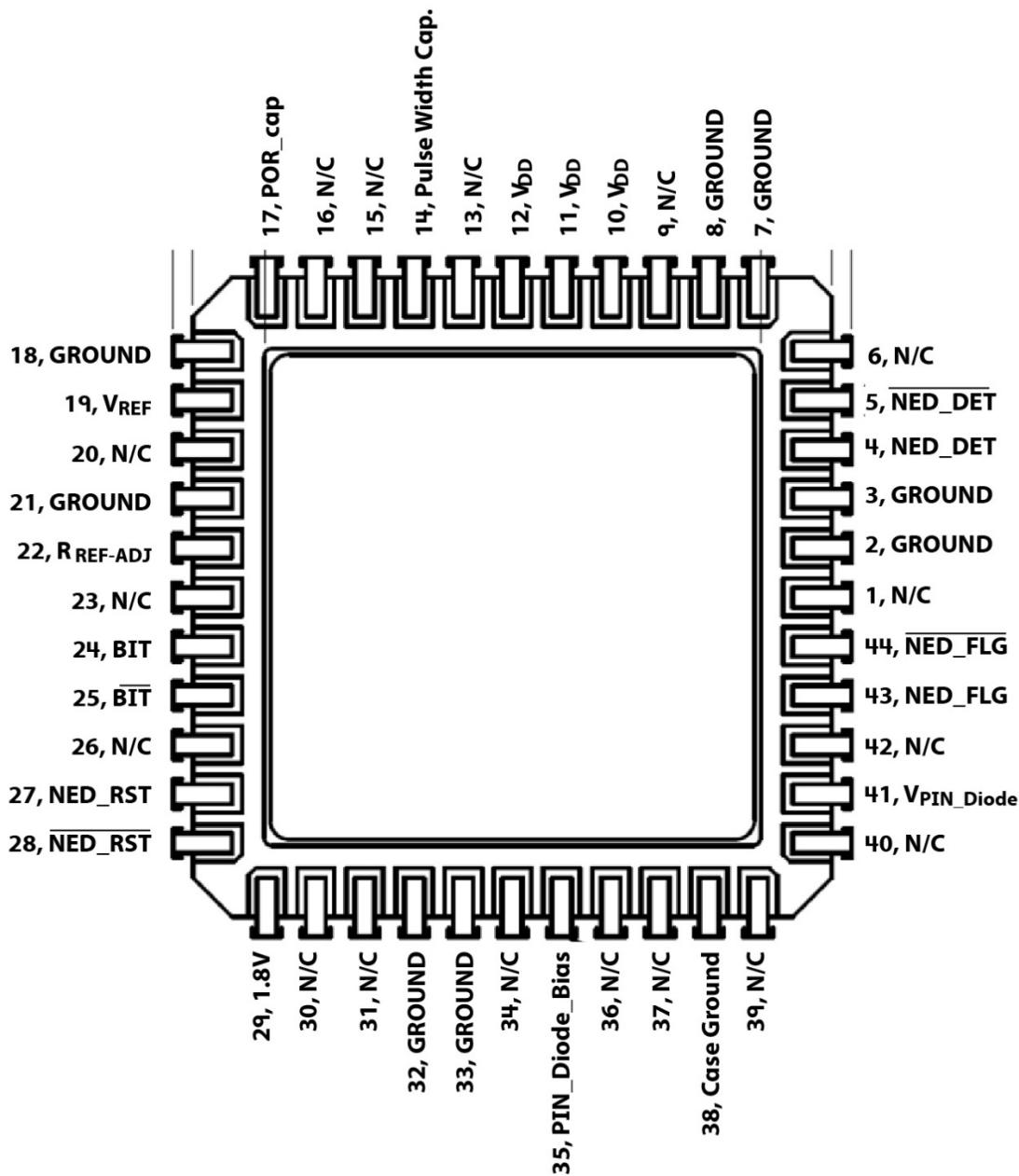


Figure 14. Top View Pinout with Signal Names

6.0 Ordering Information

MYX RH NED S CJ / H

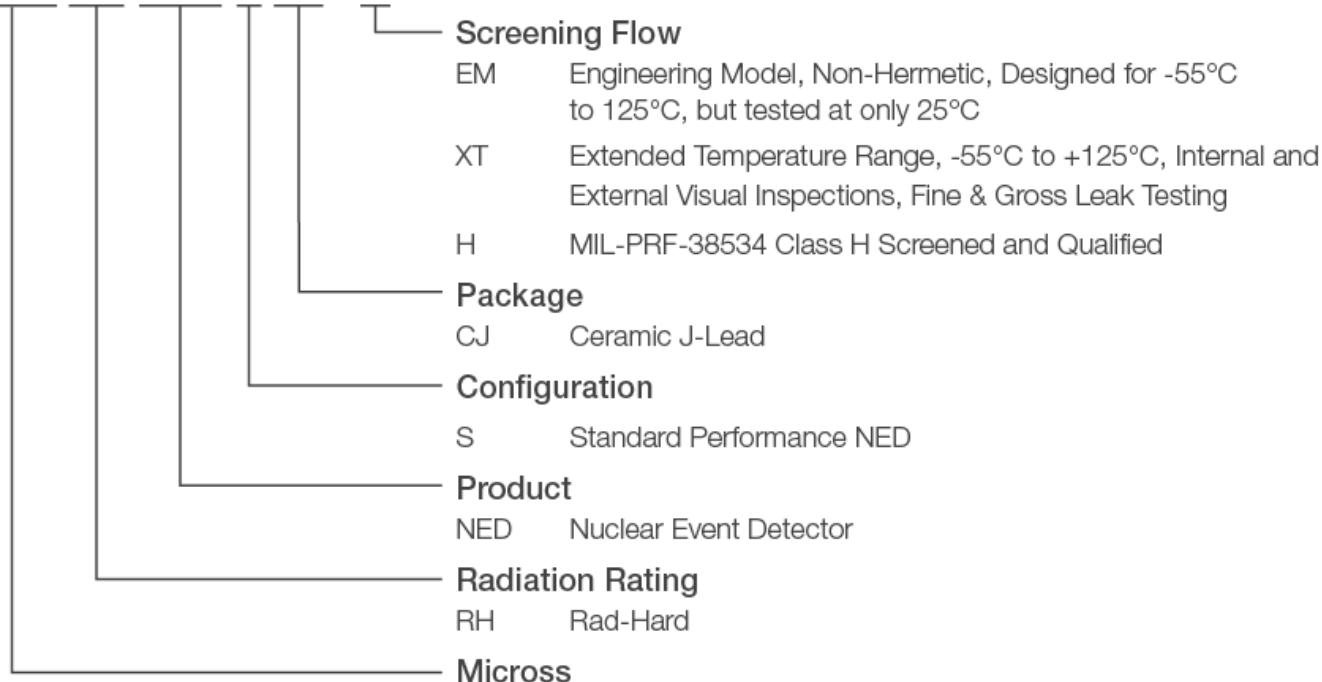


Table 4. Part Numbers

Part Number	Description
MYXRHNEDSCJ/EM	Engineering Model NED (designed for -55 to +125 °C, but tested at only 25 °C.), Standard Performance, Non-hermetic
MYXRHNEDSCJ/XT	Extended temperature (-55 to +125 °C), Standard Performance, Hermetic, tested over -55 to 125 °C and leak tested
MYXRHNEDSCJ/H	Extended temperature (-55 to +125 °C), Standard Performance, Hermetic, MIL-PRF-38534 Class H qualified

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